

Examiner's Copy

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TI **Silver**-containing tin-base solver
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PA Tokuriki Honten Kk, Japan
SO Jpn. Kokai Tokkyo Koho, 5 pp.
CODEN: JKXXAF
DT Patent
LA Japanese

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	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
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PI	JP 06269982	A2	19940927	JP 1993-58544	19930318
PRAI	JP 1993-58544		19930318		
AB	A solver contains Ag 5-20, Sn 70-90, Cu 0.05-10, Pd 0.05-2, and In and/or Ga 0.05-5%. The solder has high corrosion resistance and elec. and thermal cond. and is suitable for elec. industry.				